

/ Descriptions

SOD-523
Schottky Diode in a SOD-523 Plastic Package.

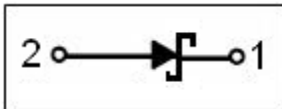
/ Features

Low forward voltage drop, HF Product.

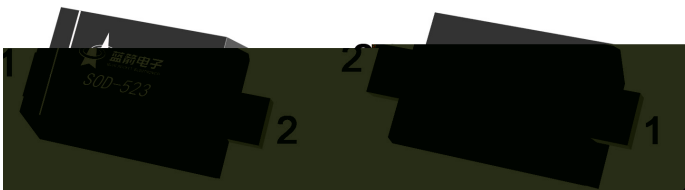
/ Applications

General purpose.

/ Equivalent Circuit

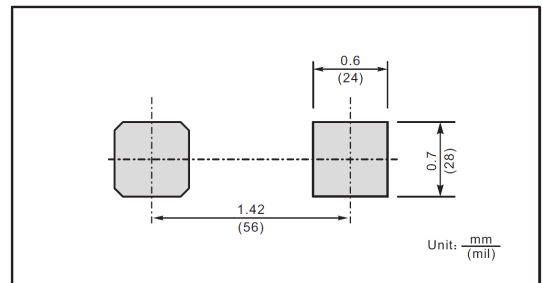


/ Pinning



PIN1: Cathode PIN2: Anode

The recommended mounting pad size



/ Marking

Type number	Marking code
RB521S-30	C

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	30	V
Forward Continuous Current	I _F	200	mA
Non-Repetitive Peak Forward Surge Current @t = 8.3ms	I _{FSM}	1	A
Power dissipation	P _D	200	mW
Junction Temperature	T _J	125	
Storage Temperature	T _{stg}	-55 to +125	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating			Unit
			Min	Typ	Max	
Reverse Breakdown Voltage	V _{BR}	I _R =500μA	30			V
Forward Voltage	V _F	I _F =20mA			0.37	V
		I _F =200mA			0.60	V
Peak Reverse Current	I _R	V _R =10V			5.0	μA

/ Electrical Characteristic Curve

Fig.1. Power Derating Curve

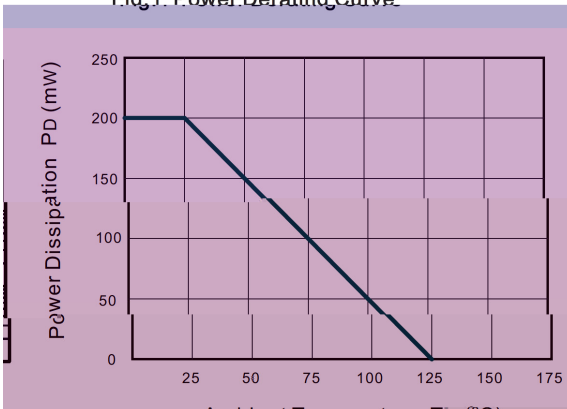


Fig.2 Typical Instantaneous Reverse Characteristics

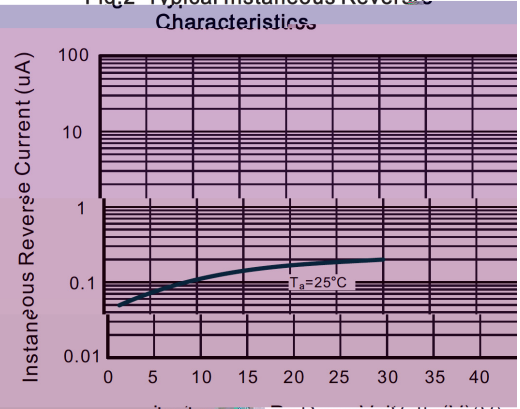
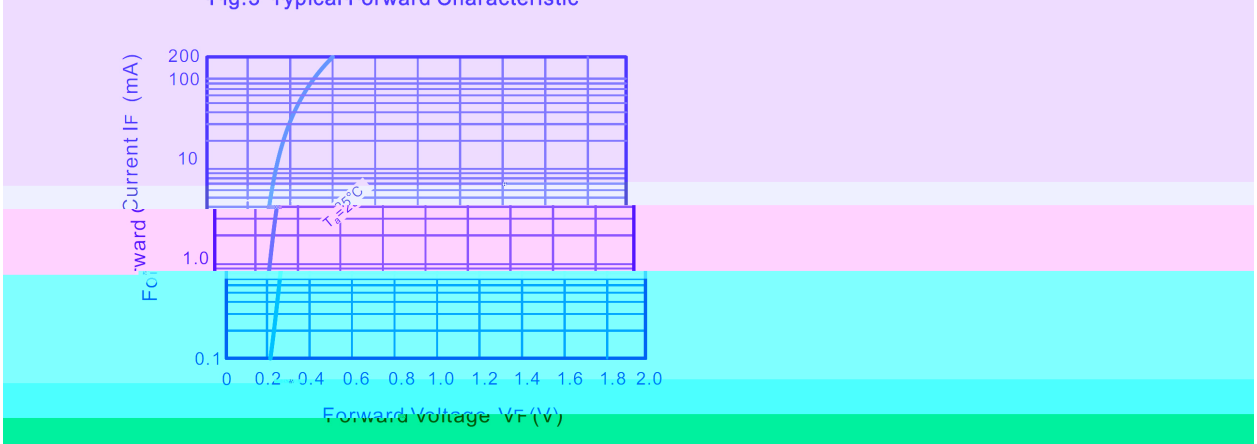
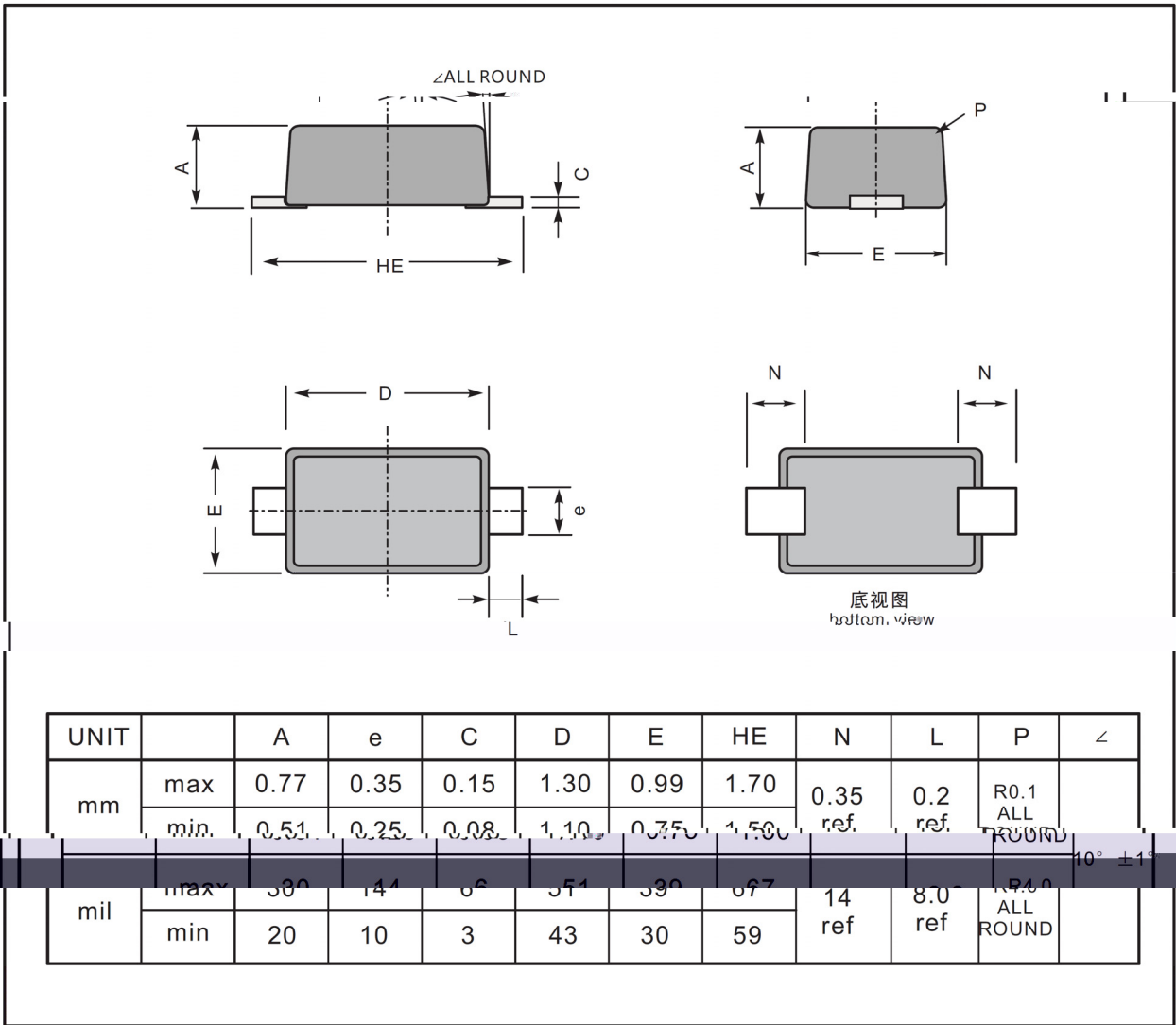


Fig.3 Typical Forward Characteristic

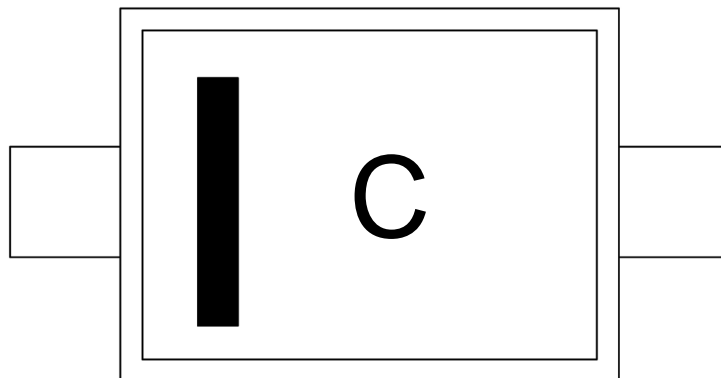


/ Package Dimensions

SOD-523



/ Marking Instructions

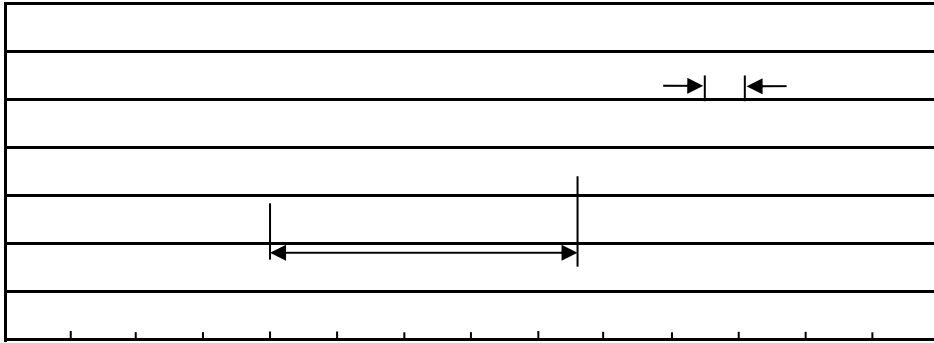


C

Note:

C : Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-523	3,000	10	30,000	6	180,000	7 x8	180x120x180	390x385x205

/ Notices